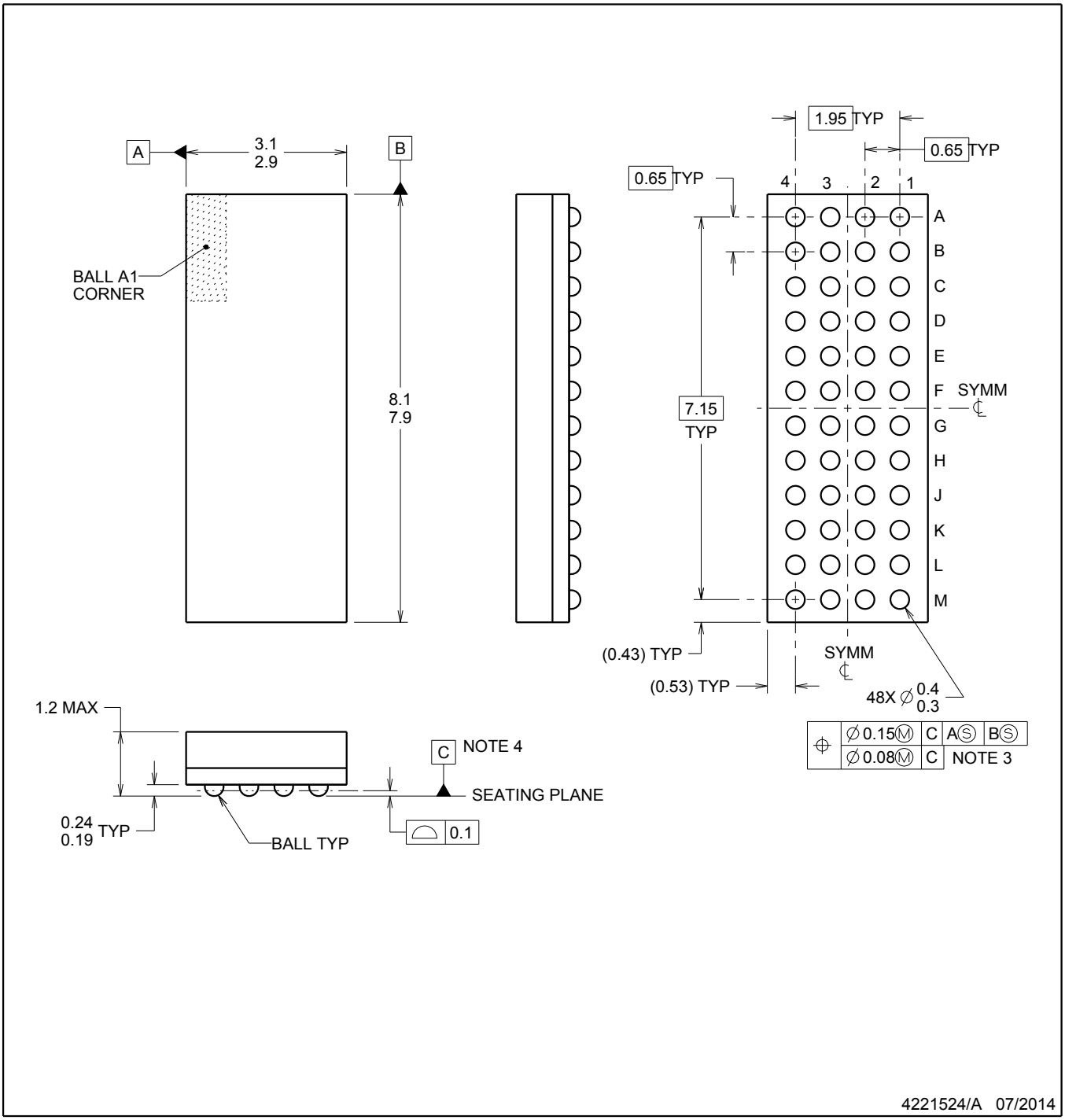
# PACKAGE OUTLINE

## ZBA0048A

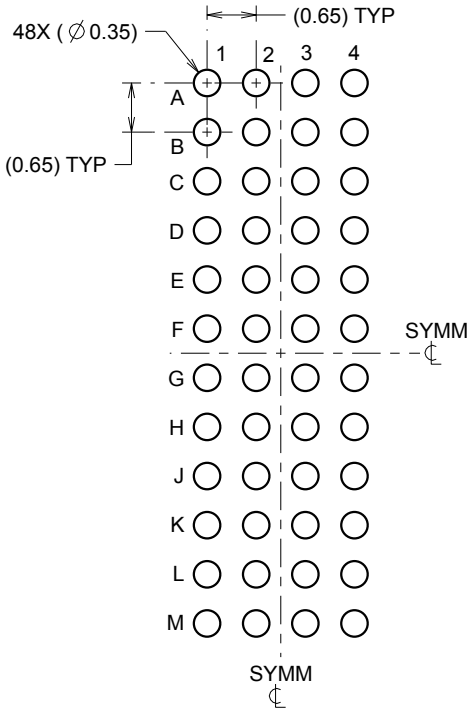
## NFBGA - 1.2 mm max height

BALL GRID ARRAY

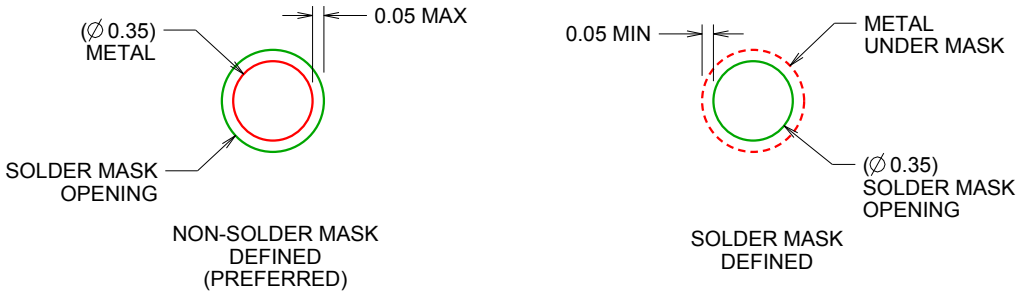



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Dimension is measured at the maximum solder ball diameter, parallel to primary datum C.
4. Primary datum C and seating plane are defined by the spherical crowns of the solder balls.




LAND PATTERN EXAMPLE
SCALE:10X




SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

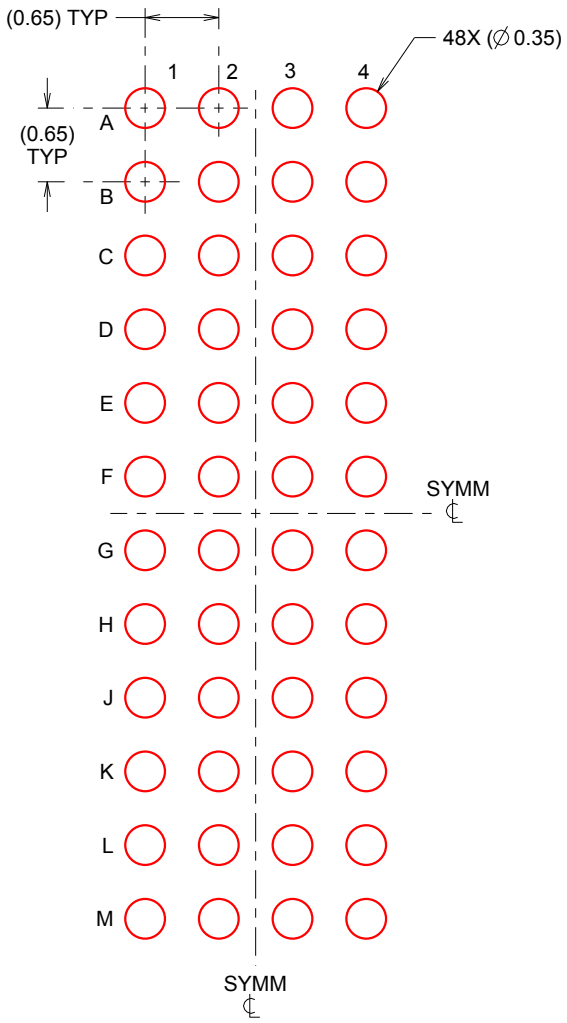
5. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints.
For more information, see Texas Instruments Literature number SPRAA99 (www.ti.com/lit/spraa99).

# EXAMPLE STENCIL DESIGN

## ZBA0048A

## NFBGA - 1.2 mm max height

BALL GRID ARRAY




SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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